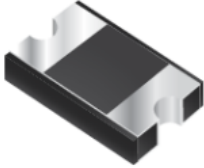


MATERIAL DECLARATION SHEET



Material Number	CD214B-S2X			
Product Line	Semiconductor Products			
Compliance Date	2019/8/2			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Metal	24.82	Continuous filament glass fibers	65997-17-3	25.10%	15.5745500%	62.05%
				Phosphorus-based epoxy resin	Confidentiality	23.11%	14.3397550%	
				Inorganic filler	Confidentiality	12.07%	7.4894350%	
				Copper	7440-50-8	39.45%	24.4787250%	
				Zinc	7440-66-6	0.20%	0.1241000%	
				Nickel	7440-02-0	0.05%	0.0310250%	
				Chromium	7440-47-3	0.01%	0.0062050%	
				Arsenic	7440-38-2	0.01%	0.0062050%	
2	Epoxy	Plastic	11.57	Silicon Dioxide	7631-86-9	57.14%	16.5277450%	28.925%
				Bis-Phenol Type Epoxy	9003-36-5	42.86%	12.3972550%	
3	Die Attach	Metal	0.88	Lead ^(Note 2)	7439-92-1	92.5%	2.0350000%	2.200%
				Tin	7440-31-5	5.0%	0.1100000%	
				Silver	7440-22-4	2.5%	0.0550000%	
4	Dice	Others	1.93	Silicon	7440-21-3	73.54%	3.5483050%	4.825%
				Nickel	7440-02-0	1.99%	0.0960175%	
				Aluminum	7429-90-5	0.56%	0.0270200%	
				Lead Glass ^(Note 3)	7439-92-1	14.80%	0.7141000%	
				Phosphorus	7723-14-0	0.249%	0.0120143%	
				Boron	7440-42-8	0.874%	0.0421705%	
5	Terminal Plating	Metal	0.8	Misc., not to declare	Confidentiality	7.987%	0.3853727%	2.000%
				Tin	7440-31-5	100%	2.0000000%	
			Total weight			40		

MATERIAL DECLARATION SHEET



This Document was updated on: 2019/8/2

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption 7(a): Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)
3. RoHS exemption 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezo-electronic devices, or in a glass or ceramic matrix compound